

High Voltage Amplifier with Discrete Output Current Boost

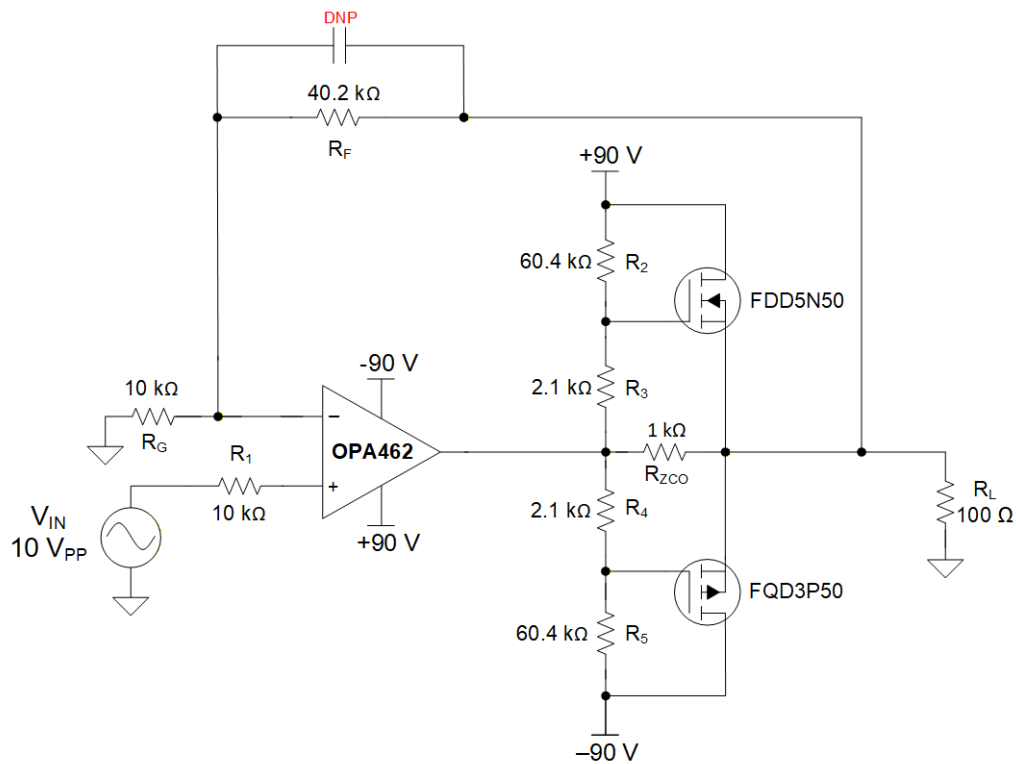


Design Goals

| Input | | | Output | |
|-------------------|-----------|------|-------------------|-----------|
| V_{IN} | Bandwidth | Gain | V_{OUT} | I_{OUT} |
| 10V _{PP} | 20kHz | 5V/V | 50V _{PP} | 500mA |

Design Description

This circuit implements a non-inverting amplifier with a gain of 5 to drive discrete complementary output transistors. This circuit is capable of delivering 500mA at 20kHz with negligible distortion. This circuit is designed to be operated at $\pm 90V$.



OPA462 Discrete Output Current Boost Circuit

Design Notes

1. A voltage divider network (R_2 , R_3 , R_4 , and R_5) provides nominal voltage to bias V_{GS} . It is essential to choose a voltage bias network that minimizes crossover distortion, but does not cause cross conduction, as this can damage the metal-oxide-semiconductor field-effect transistors (MOSFETs) and surrounding circuit. Cross conduction occurs when both MOSFETs are on at the same time. This can cause large current surges and thermal runaway which can damage the circuit.
2. Select a high voltage op amp to maximize the output swing of the circuit.
3. Bandwidth is a function of the closed loop gain, as seen from the equation below. Selecting an amplifier with a large gain bandwidth allows for wider frequency response.

$$\text{Closed Loop Bandwidth} = \frac{\text{Gain Bandwidth Product}}{ACL} \quad (1)$$

4. Verify input voltage is within the full power bandwidth and output voltage specifications for the given op amp. For a ± 90 V supply, slew induced distortion will become significant above 50kHz (see Figure 28 from [OPA462 datasheet](#)). This can also be calculated using the equation:

$$V_{pk} = \frac{\text{Slew Rate}}{2 \times \pi \times f} \quad (2)$$

Distortion becomes more significant the closer the output voltage is to the power supply rails. However, distortion in the output crossover region, resulting from the switching characteristics of the discrete transistors, differs from slew-rate-induced distortion. This crossover distortion is also dependent on the input and output capacitance of the transistors, and difficult to calculate empirically. Therefore, the best approach to determine if the desired input frequency is feasible is to simulate the circuit.

5. When designing the voltage divider, use smaller resistor values to lessen the transition time between the push-pull pair. The gate resistor and input capacitance of the MOSFET (FET) determines the RC time constant. Therefore, the smaller the resistor, the faster the FET will switch on. However, smaller resistor values increase the current consumption through the bias path, so it is important to be aware of this trade-off. In this example design, R_2 and R_5 were chosen to be 60.4k Ω for best results.
6. Careful consideration of the characteristics and trade-offs between bipolar junction transistors (BJTs) and MOSFETs is essential when choosing a discrete complementary output stage (see Table 3-1 from the application note [Optimizing Dual Feedback Compensation in the OPA593 With a Current Booster](#) for further detail).
7. Including a footprint for a compensation capacitor C_F is recommended to provide flexibility for stability optimization. Instability can result from capacitive loading at the output node, large feedback resistors, or capacitance on the inverting input. Refer to the [Operational Amplifier Stability Theory and Compensation Methods](#) technical paper for a detailed discussion of op amp stability and compensation methods.
8. Components in output path of the transistors, such as the load resistor, R_L , must have adequate power ratings. High voltage and high-power PCB layout guidelines should also be followed (see the [TIPL training on Power and Temperature](#)). Consider using a fan to help reduce the heat that the circuit can generate.

Design Steps

1. Calculate maximum output current for given Gain and R_L .

$$\text{Given: } V_{IN} = 10V_{PP}, \quad R_G = 10k\Omega, \quad R_F = 40.2k\Omega, \quad R_L = 100\Omega \quad (3)$$

$$I_{OUT} = \frac{V_{OUT}}{R_L} = \frac{V_{IN} \left(\frac{R_F}{R_G} + 1 \right)}{R_L} = \frac{10 \left(\frac{40.2k\Omega}{10k\Omega} + 1 \right)}{100\Omega} = 500.2mA \quad (4)$$

2. Calculate the output power of the circuit and select MOSFETs with appropriate power dissipation capabilities. The output FET power will be a function of the load, output voltage and supply voltage. For resistive loads, with the load ground-referenced, the power will peak when the output voltage is halfway between ground and the supply voltage. The peak current the FET will consume is 500mA, with the TINA-TI simulation results showing a maximum output power of approximately 16.2W. Note that the output of the amplifier is significantly lower, consuming less than 300mW of power, demonstrating the benefits of this circuit configuration. Select MOSFETs that have greater than 30W of power dissipation capability, such as FDD5N50 and FQD3P50, which have a power dissipation of at least 50W. The maximum power dissipation at the output stage with a resistive load can be calculated using the following equation. Note that power consumption will vary with the load type (resistive vs. current). Refer to the [TIPL on Power and Temperature](#) for further details.

$$P_{AC_MAX_AVG} = \frac{2 \times V_{CC}^2}{\pi^2 \times R_L} \quad (5)$$

$$P_{AC_MAX_AVG} = \frac{2 \times (90V)^2}{\pi^2 \times 100\Omega} \quad (6)$$

$$P_{AC_MAX_VG} = 16.414W \quad (7)$$

3. Select a zero-crossover resistor (R_{ZCO}) that provides sufficient current to drive the circuit while the MOSFETs are off. During this period, the R_{ZCO} is driving the load. Consider the trade-offs when selecting the R_{ZCO} . R_{ZCO} must be high enough to avoid current limit of the amplifier, but low enough to minimize noise and crossover distortion. A large R_{ZCO} , when paired with a capacitive load, can result in slower transients. However, a larger R_{ZCO} results in lower power dissipation.

The value of R_{ZCO} can be iteratively determined through simulation. The results shown below demonstrate that resistor values below 100 Ω cannot drive the loop when the MOSFETs are off. The 499 Ω resistor value drives 10.1 mA of current, while the 1k Ω drives 5.05mA of current. The 1k Ω resistor has a thermal noise of approximately 4 nV/ $\sqrt{\text{Hz}}$, which is smaller than the op amp voltage noise of 23nV/ $\sqrt{\text{Hz}}$. Therefore, 1k Ω is a good choice for the R_{ZCO} , optimizing for both voltage noise and low power dissipation.

4. Calculate the voltage divider resistor values based on the V_{TH} of the selected MOSFET or BJT. To minimize power dissipation from VCC and VEE, use relatively large resistance for R_2 and R_5 .

$$\text{Given: } R_2 = R_5 = 60.4 \text{ k}\Omega.$$

From the FDD5N50 datasheet, $3 \text{ V} < V_{GS(th)} < 5 \text{ V}$.

Optimize the resistor divider network by selecting R_3 and R_4 such that $V_{GS(th)} = 3 \text{ V}$.

Set V_{GS} to nominal value 3V to optimize for crossover distortion without cross conduction.

$$V_{GS} = \frac{R_3}{R_2 + R_3} \times V_{CC} \quad (8)$$

$$3V = \frac{R_3}{60.4k\Omega + R_3} \times 90V \quad (9)$$

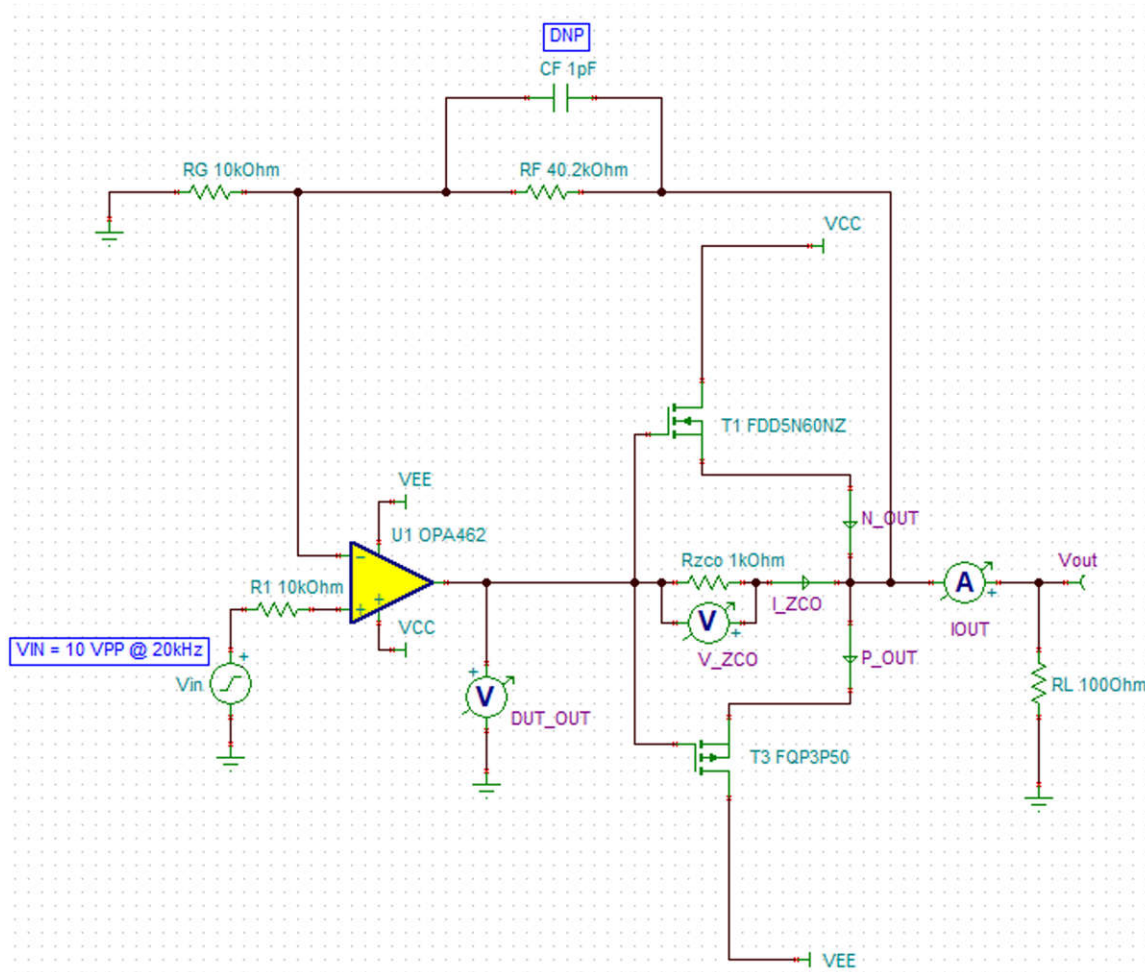
$$R_3 = 2082.76\Omega \quad (10)$$

Choose standard resistor value such that $R_3 = 2.1k\Omega$.

$$\therefore R_3 = R_4 = 2.1k\Omega \quad (11)$$

R_3 and R_4 can be further optimized for crossover distortion empirically, as individual $V_{GS(th)}$ values for the chosen MOSFETs will vary due to process variation. However, caution should be used, as there is a possibility for cross conduction if V_{GS} is too high.

Design Simulation Results

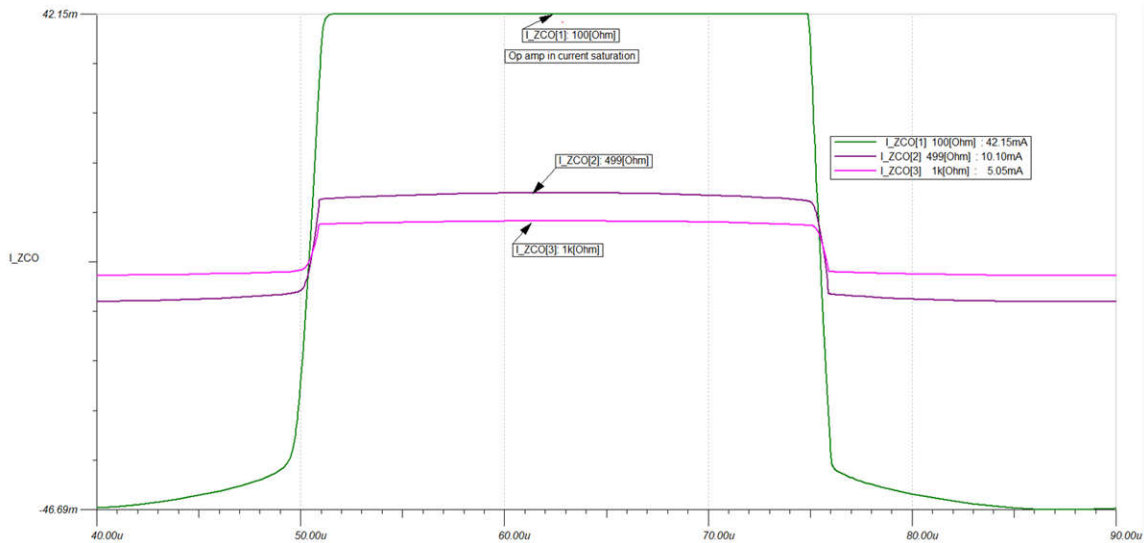


OPA462 Discrete Output Current Boost R_{ZCO} TINA Circuit

Note

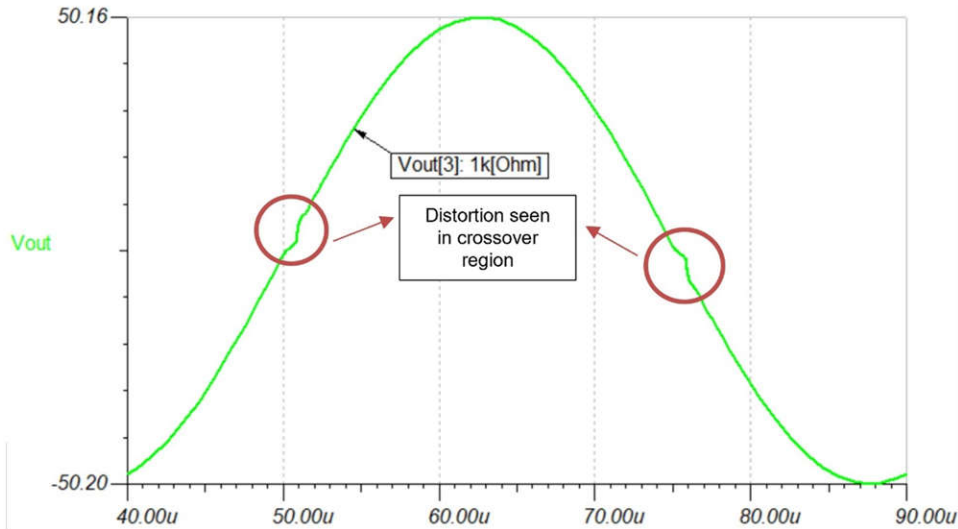
The SPICE model FDD5N60NZ was used for modeling as there is no model available for the 500V version of the NMOS. The characteristics are similar enough to provide a close approximation for simulation results.

TINA simulations are run originally without the voltage divider as part of the circuit. This allows for insight into the optimized value of R_{ZCO} . Later we will add a voltage divider to the circuit to further optimize crossover distortion.



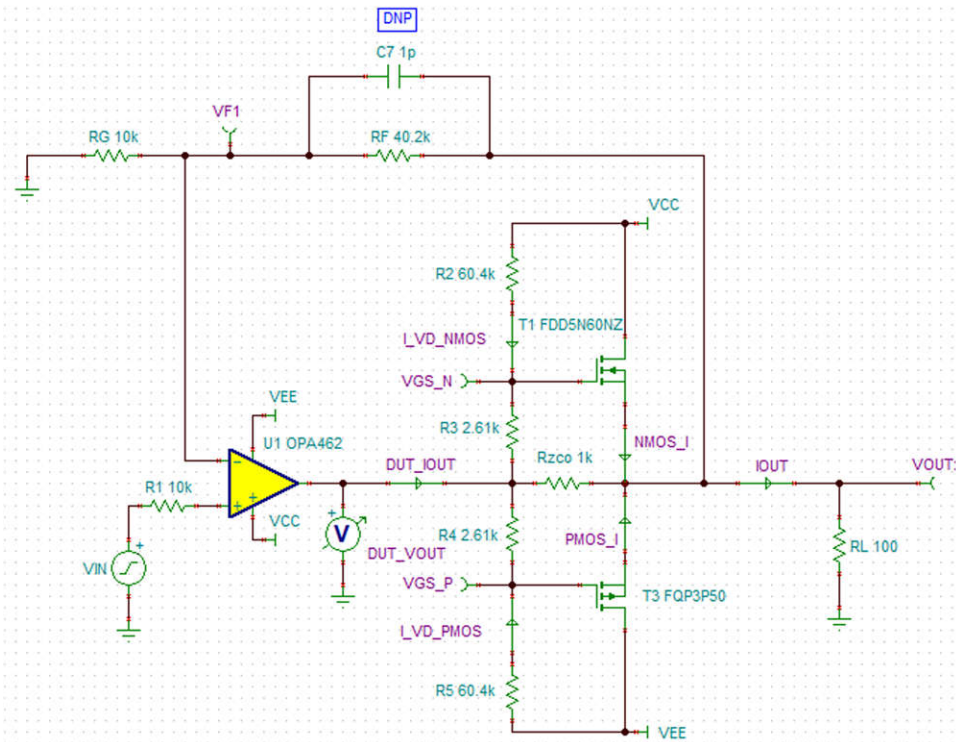
Simulation Results for R_{ZCO} and Corresponding I_{ZCO} Values

A $10V_{PP}$ square wave is applied to the input of the circuit. The output response provides insight into the current driving the load when the MOSFETs are turned off. Selecting R_{ZCO} resistors that are too low ($100\ \Omega$, $499\ \Omega$) result in excessive current flow (labelled I_{ZCO}) from the output of the amplifier. Here, $1k\ \Omega$ was chosen for R_{ZCO} as it adds 5 mA of current to the circuit, as opposed to the 10 mA of current consumption with the $499\ \Omega$ resistor (see [Simulation Results for \$R_{ZCO}\$ and Corresponding \$I_{ZCO}\$ Values](#)). Furthermore, the noise difference between the $499\ \Omega$ resistor and the $1k\ \Omega$ resistor is minimal, making $1k\ \Omega$ a preferred choice for R_{ZCO} . A larger resistor can be used but adds additional noise to the circuit.

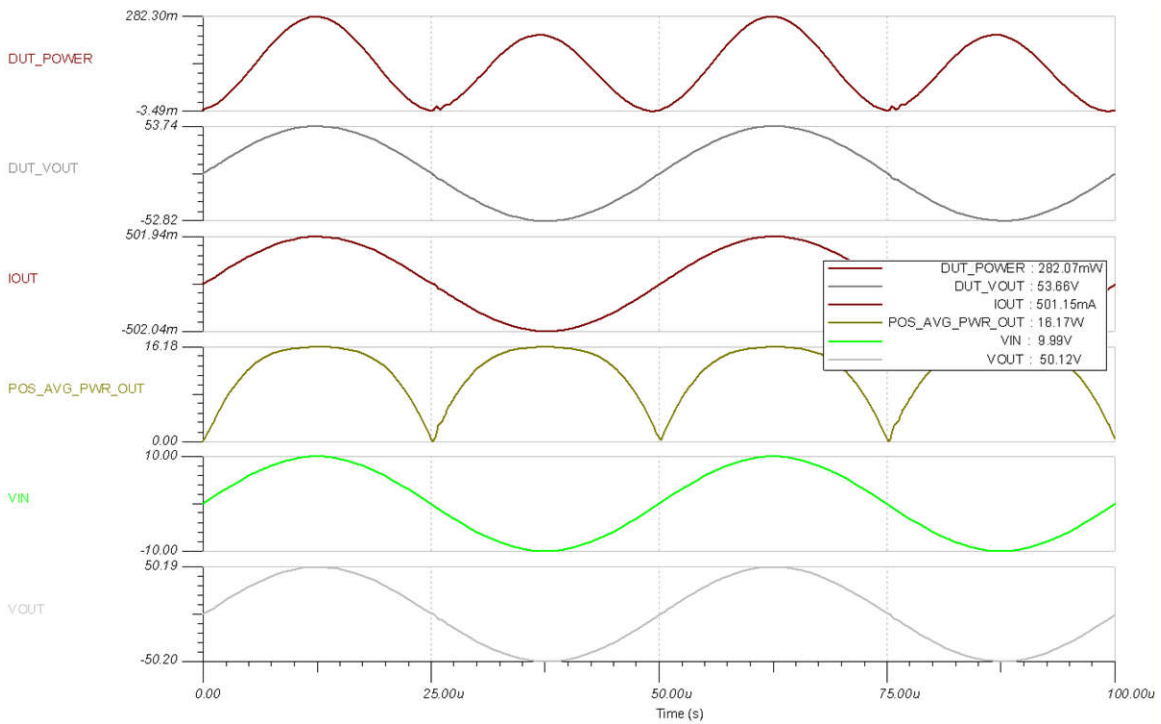


Simulation Results for V_{OUT} Distribution for $R_{ZCO} = 1k\ \Omega$

The distortion is minimized with $R_{ZCO} = 1k\ \Omega$, but there is still crossover distortion in the circuit. Adding a voltage divider to the circuit allows for further optimization, as seen in the [OPA462 Discrete Output Boost TINA Circuit](#) figure.



OPA462 Discrete Output Current Boost TINA Circuit



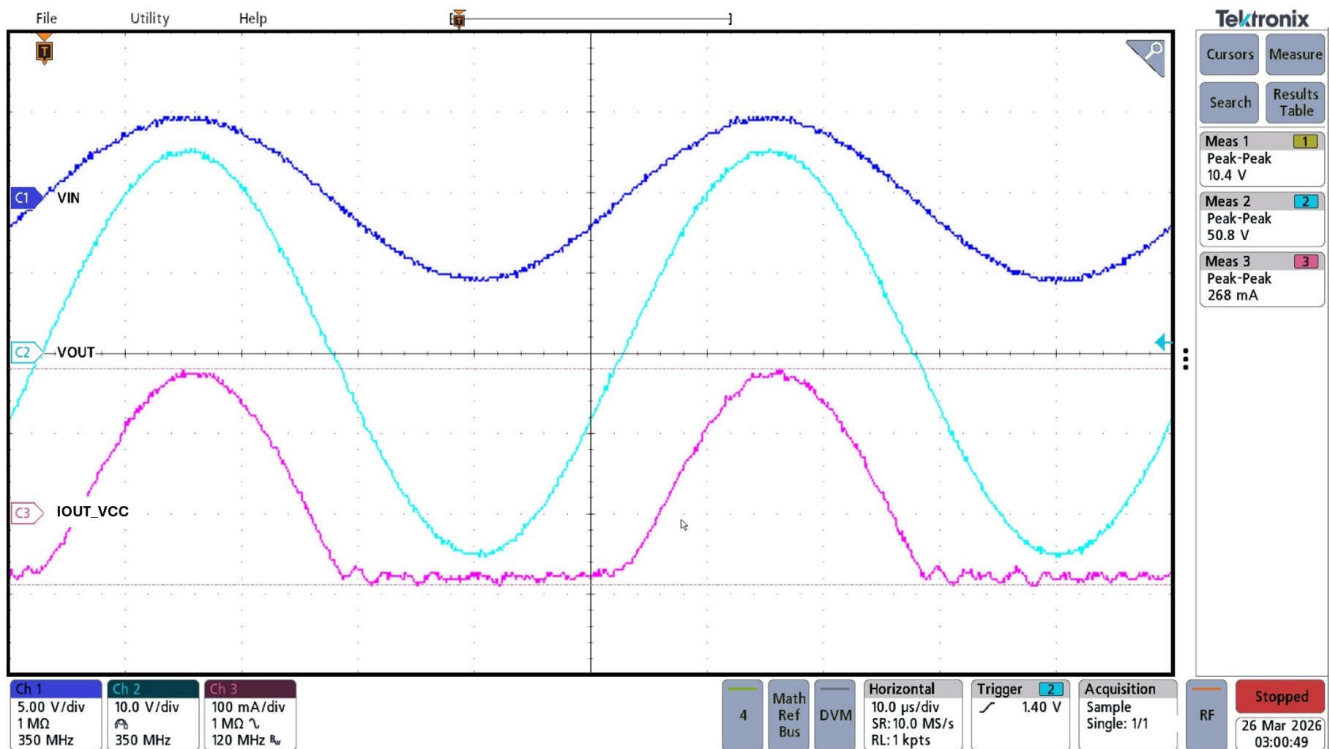
OPA462 Discrete Output Current Boost Circuit Simulation Results

The voltage divider was added to the circuit and further minimizes cross over distortion on the output of the circuit. The post processor in TINA is used to calculate the average output power of the circuit. Additionally, the post processor is used to show the output power of the OPA462 is minimal, approximately 300mW (labeled DUT_POWER).

Design Measured Results

R_3 was iteratively increased to find the optimal value for minimal crossover. A value of $R_3 = R_4 = 2.67\text{k}\Omega$ was found to optimize the circuit while allowing for minimal distortion. See below for oscilloscope results for the circuit.

| Input | | | Output | |
|--------------------|-----------|------|-------------------|-----------|
| V_{IN} | Bandwidth | Gain | V_{OUT} | I_{OUT} |
| 10 V _{PP} | 20kHz | 5V/V | 50V _{PP} | 500mA |

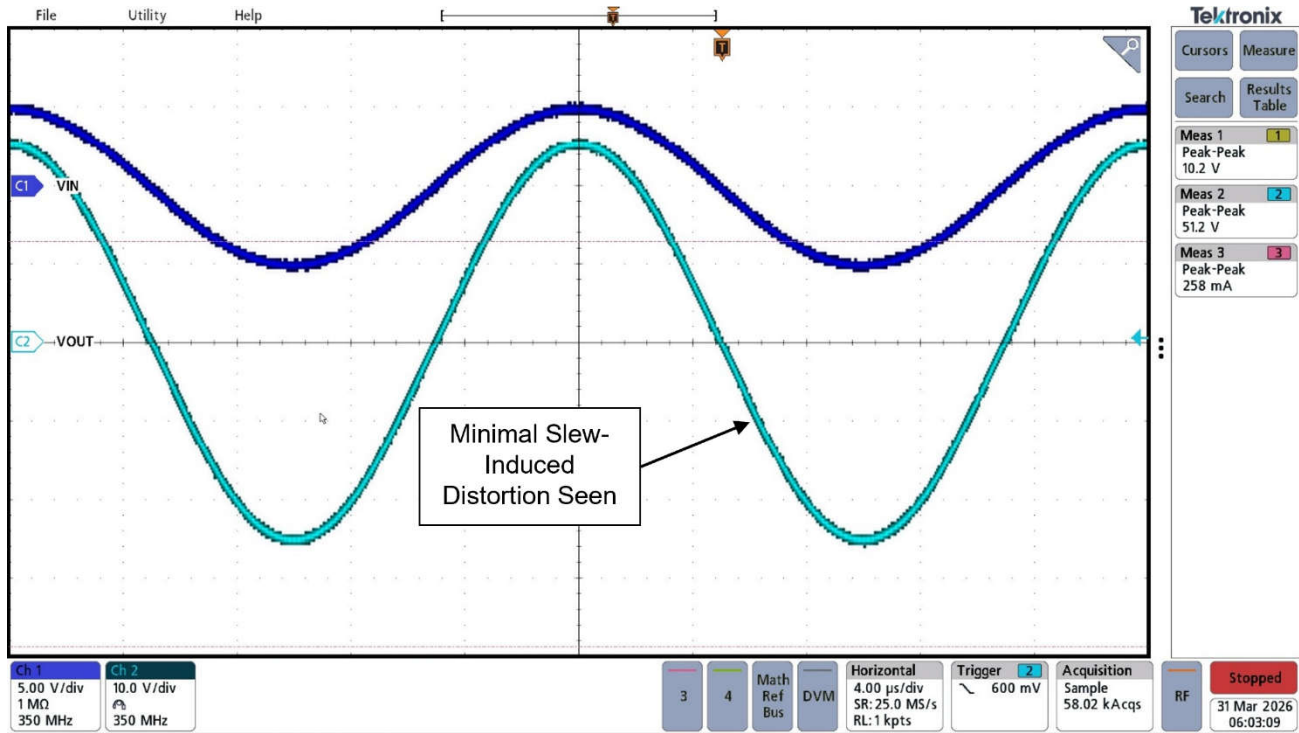


OPA462 Discrete Output Current Boost Circuit Measured Results ($V_{IN} = 10V_{PP}$ @ 20 kHz)

Note

The IOU_VCC measurement is measured from VCC. No visible distortion is seen at VOUT.

| Input | | | Output | |
|-------------------|-----------|------|-------------------|-----------|
| V_{IN} | Bandwidth | Gain | V_{OUT} | I_{OUT} |
| 10V _{PP} | 50kHz | 5V/V | 50V _{PP} | 500mA |



OPA462 Discrete Output Current Boost Circuit Measured Results ($V_{IN} = 10V_{PP}$ @ 50 kHz)

Note

Minimal slew-induced distortion is seen at VOUT, but the amplitude of the sine wave is not affected.

Target Applications

- High Voltage/High Signal Generator
- Parametric Measurement Unit
- Source Measurement Unit

Design Featured Devices

| OPA462 | |
|------------------------|---|
| V_{SS} | 12V to 180V |
| V_{OUT} | (V-) + 3 to (V+) -1.5 (with $R_L = 10k\Omega$) |
| V_{OS} | 3.4mV |
| I_Q | 3.2mA |
| Unity Gain Bandwidth | 6.5MHz |
| Slew Rate | 32V/ μ s |
| OPA462 | |

Design Alternative Devices

| OPA455 | |
|------------------------|--|
| V _{SS} | 12V to 150V |
| V _{OUT} | (V-) + 3 to (V+) -1.5 (with R _L = 10kΩ) |
| V _{OS} | 3.4mV |
| I _Q | 3.2mA |
| Unity Gain Bandwidth | 6.5MHz |
| Slew Rate | 32V/μs |
| OPA455 | |

Design References

1. Texas Instruments, OPA462 Discrete Output Current Boost Circuit, TINA-TI simulation files [SBOMCU1](#)
2. Texas Instruments, [OPA462 TINA-TI Spice Model](#)

Additional Resources

Trademarks

All trademarks are the property of their respective owners.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025